

## **THERMAL DISSIPATION IN INTEGRATED CIRCUIT SYSTEMS**

### **ABSTRACT**

Integrated circuit systems with thermal dissipation enhancement features are described. In one aspect, an integrated circuit system includes a die  
5 incorporating an integrated circuit. The die has a top side and a bottom side. The top side supports an electrical signal communication metallization and a top side thermal dissipation metallization. The bottom side supports a bottom side thermal dissipation metallization.